

Surface Mount Super Fast Recovery Rectifier Diode

Features

- Very Low Profile: Typical Height of 1.1 mm
- Ultrafast Recovery Time
- Low Forward Voltage Drop
- Low Thermal Resistance
- Very Stable Operation at Industrial Temperature, 150°C
- RoHS Compliant
- Green Molding Compound as per IEC61249 Standard
- Lead Free in Compliance with EU RoHS 2011/65/EU Directive
- With DAP Option Only

Maximum Ratings

Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage TES10D TES10G TES10J	V_{RRM}	200 400 600	V
Average Forward Rectified Current	$I_{F(AV)}$	10	A
Peak Forward Surge Current: 8.3 ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	150	A
Operating Junction Temperature Range	T_J	-55 to +150	°C
Storage Temperature Range	T_{STG}	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

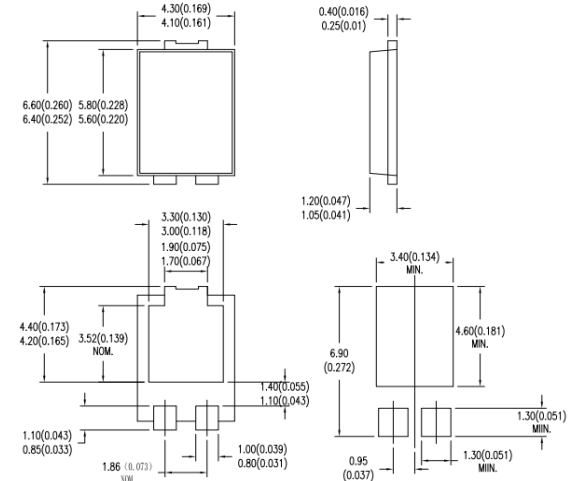
Symbol	Parameter	Conditions	Value			Unit
			TES10D	TES10G	TES10J	
V _F	Maximum Instantaneous Forward Voltage (Note 2)	I _F = 10 A	0.95	1.30	1.80	V
I _R	Maximum Reverse Current at Rated V _R	T _J = 25°C	5			μA
		T _J = 125°C	250	500		
C _J	Typical Junction Capacitance	V _R = 4 V, f = 1 MHz	140			pF
T _{rr}	Typical Reverse Recovery Time	I _F = 0.5 A, I _R = 1 A, I _{RR} = 0.25 A	35			ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse test with $PW = 300\text{ }\mu\text{s}$, 1% duty cycle

TO-277B

Cathode & Heatsink  Anode 1
Anode 2





Thermal Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Thermal Characteristics, Junction-to-Lead, Thermocouple Soldered to Cathode	$R_{\theta JL}$	6	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	100	$^\circ\text{C/W}$

1. Per JESD51-3 Recommended Thermal Test Board.

Thermal Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

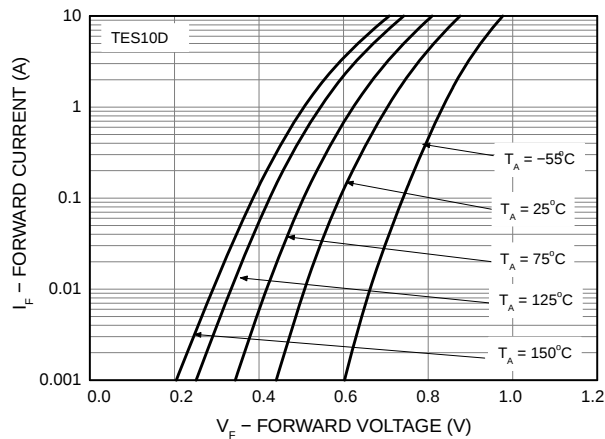


Fig 1. Typical Forward Characteristics for TES10D

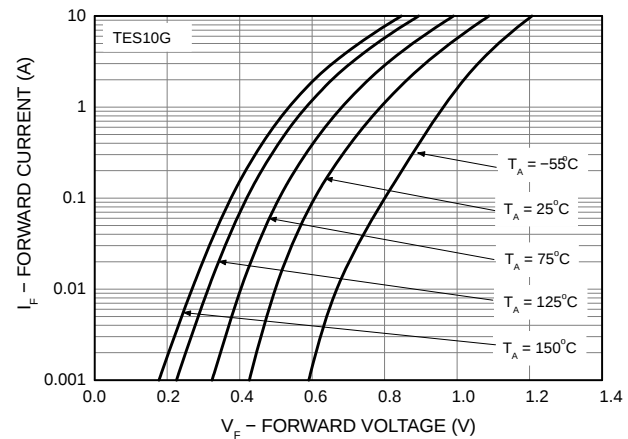


Fig 2. Typical Forward Characteristics for TES10G

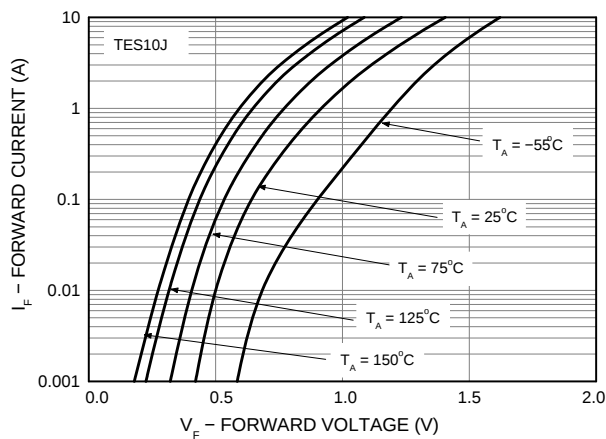


Fig 3. Typical Forward Characteristics for TES10J

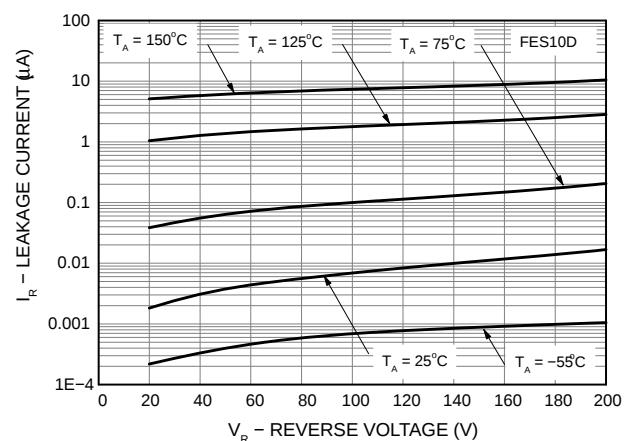


Fig 4. Typical Reverse Characteristics for TES10D

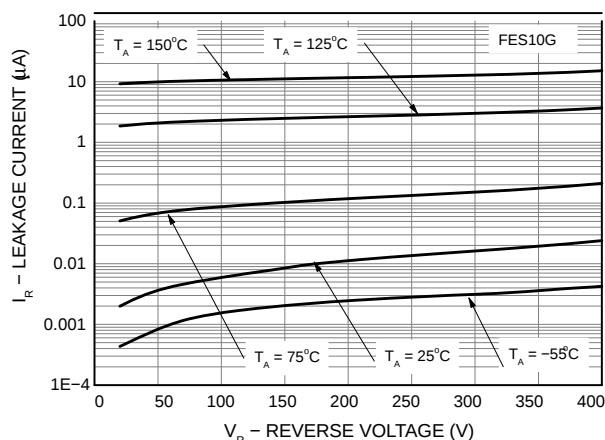


Fig 5. Typical Reverse Characteristics for TES10G

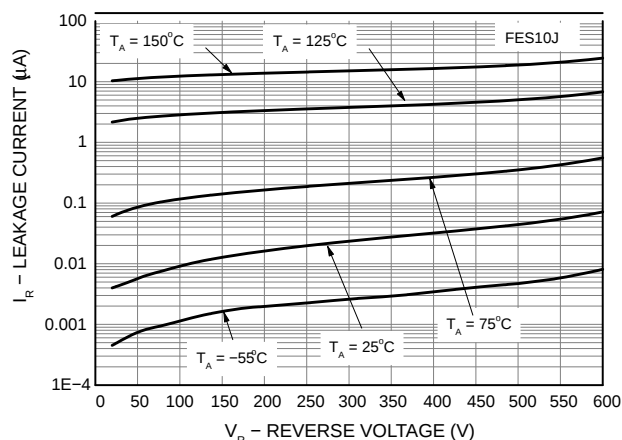


Fig 6. Typical Reverse Characteristics for TES10J

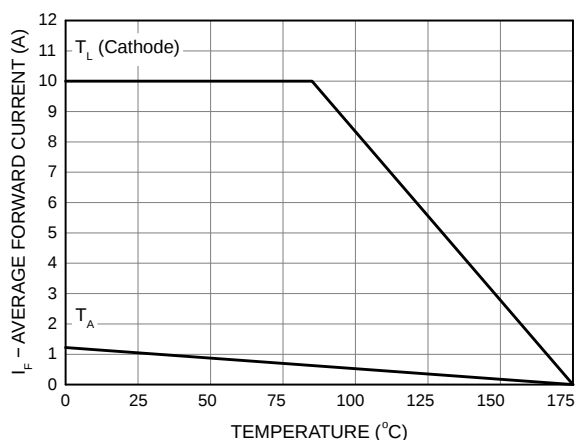


Fig 7. Forward Current Derating Curve

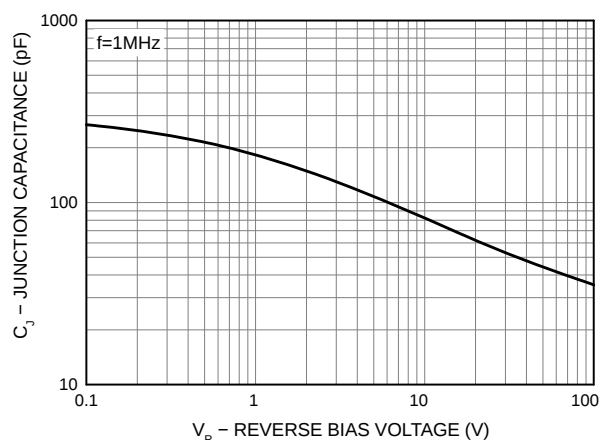


Fig 8. Typical Junction Capacitance